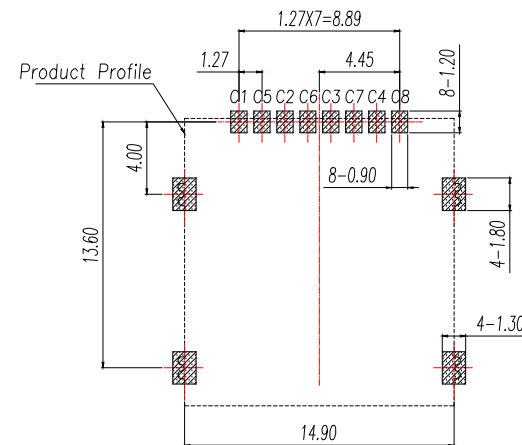
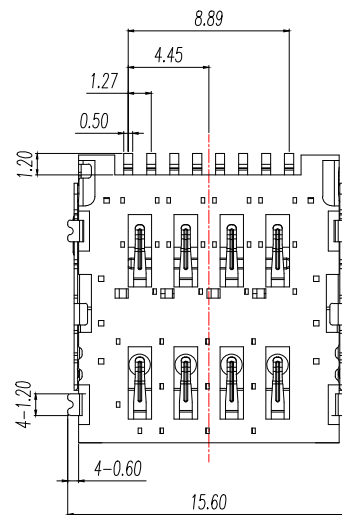
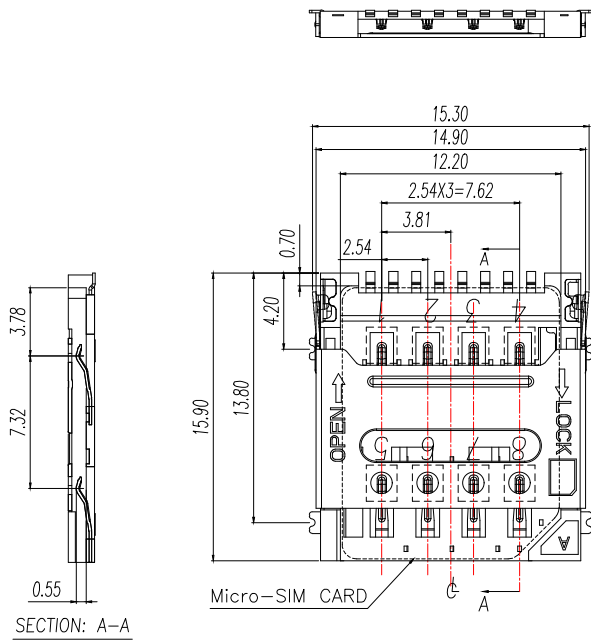


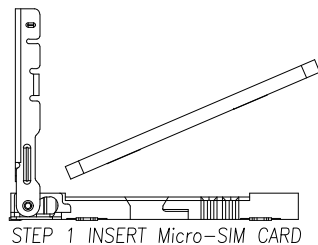
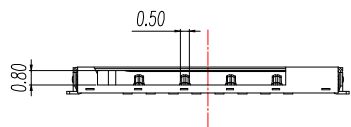


PAD AREA

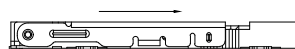
KEEP OUT AREA

RECOMMENDED PCB LAYOUT

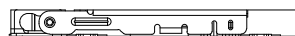
GENERAL TOLERANCE ± 0.05



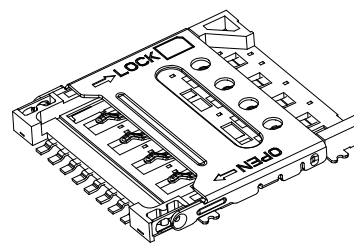
STEP 1 INSERT Micro-SIM CARD



STEP 2 PUSH THE SHELL

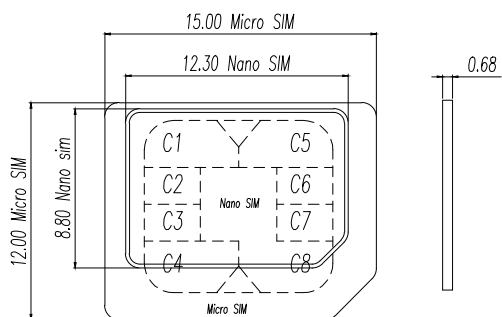
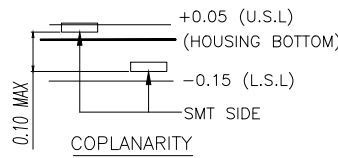


STEP 3 FINISH



NOTES:

- ELECTRICAL CHARACTERISTICS
1-1. CONTACT RESISTANCE: 60 MILLIOHMS MAX
1-2. INSULATION RESISTANCE: 1,000 MEGOHMS MIN.
1-3. DIELECTRIC WITHSTANDING VOLTAGE: 500V AC FOR 1 MINUTE.
- MECHANICAL CHARACTERISTICS
2-1. OPERATION TEMPERATURE RANGE: $-25^{\circ}\text{C}\sim+70^{\circ}\text{C}$
2-2. DURABILITY: 5000 CYCLES
- MATERIAL:
3-1. HOUSING: THERMOPLASTIC, UL 94-V0
3-2. TERMINAL: PHOSPHOR BRONZE, $T=0.15$
3-3. SHELL: STAINLESS STEEL, $T=0.15$
- FINISHED:
4-1. TERMINAL: NI PLATED UNDER, AU PLATED ON CONTACT AREA, G/F PLATED ON SOLDER TAIL

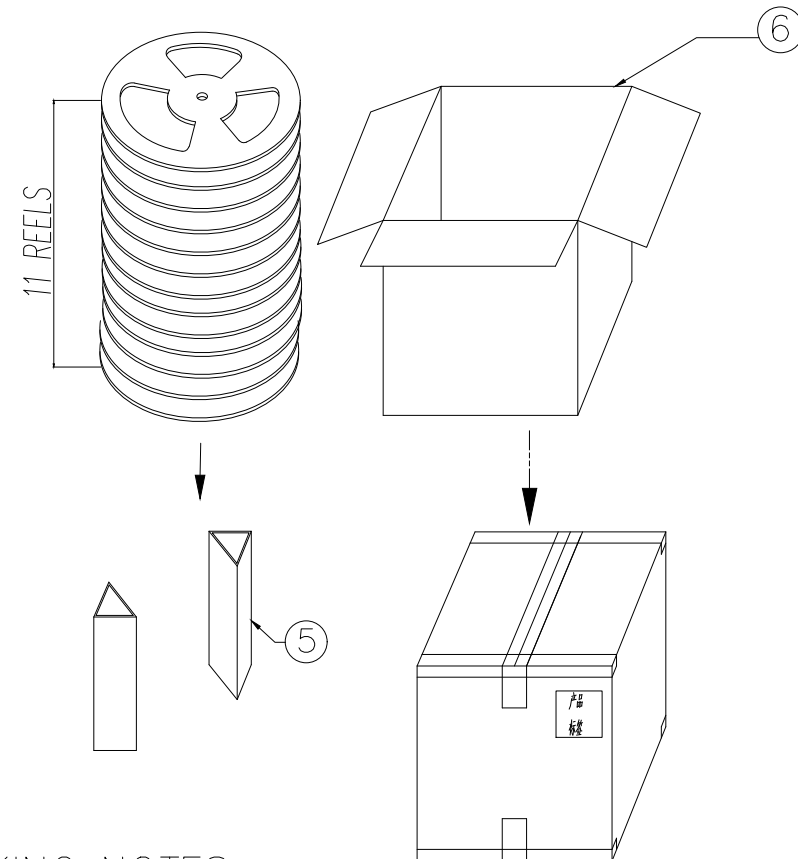
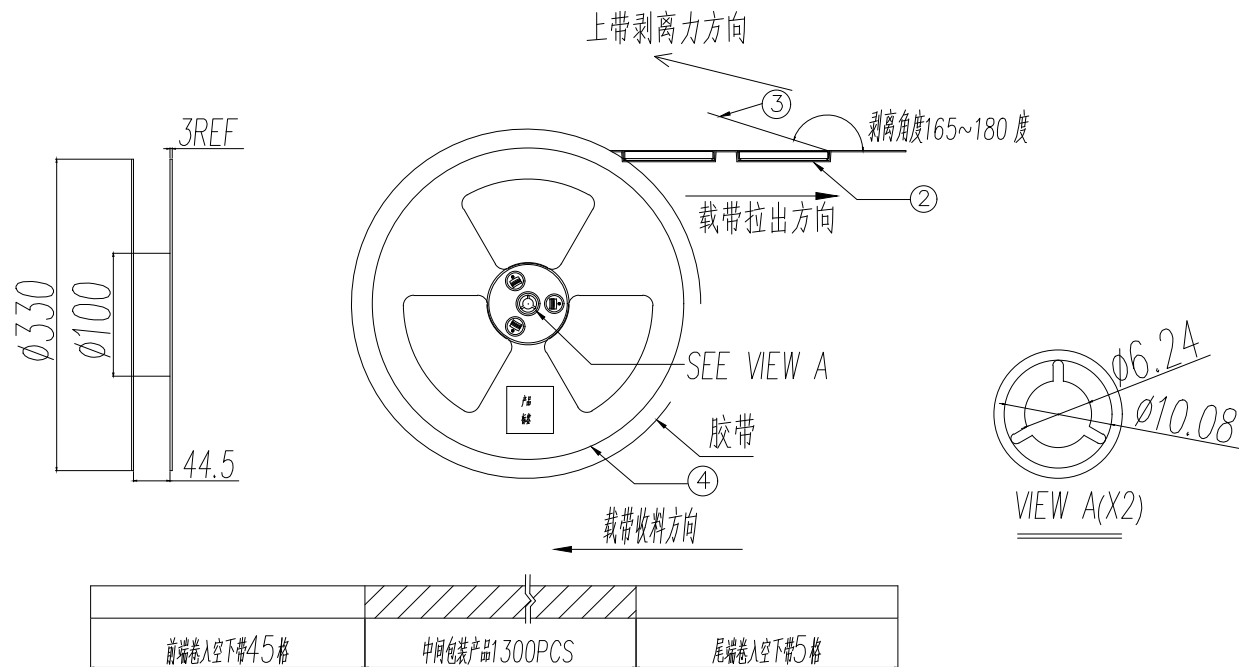


制图 DRAWN	变更内容 DESCRIPTION	日期 DATE	GENERAL TOLERANCE		审核 CHECK	批准 APPROVAL	单位 UNITS	比例 SCALE	1:1
			X ± 0.50	X' $\pm 5^{\circ}$					
			.X ± 0.25	.X' $\pm 3^{\circ}$					
			.XX ± 0.12						

EMMA	MM	SCALE	1:1
EVA			
JADE			

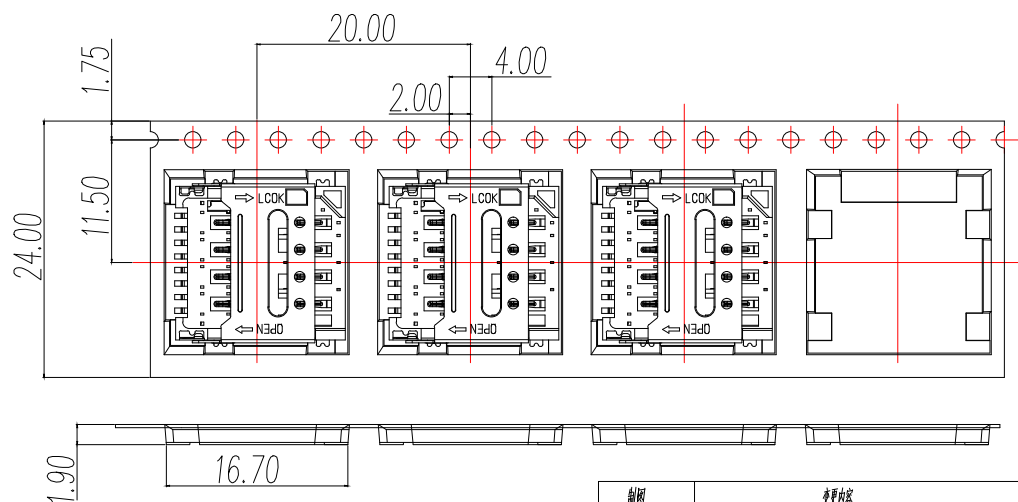
MICRO SIM CARD			
Pin No.	NAME		
C1	VCC OF SIM		
C2	RST OF SIM		
C3	CLK OF SIM		
C5	GND OF SIM		
C6	VPP OF SIM		
C7	I/O OF SIM		
C4/C8	N/A		

料号 PART NO.	BX-SIM-1.5HJ	版本 REV.	A
品名 TITLE	MICRO SIM CARD HINGED 8PIN H1.5 封装	页次 SHEET	1/1
客户料号 CUTM.NO.			



PACKING NOTES:

1. PRIMARY PACKING: 1300PCS/REEL;
2. SECONDARY PACKING: 10 REELS/CARTON (13KPCS/CARTON)
3. PEELING RESISTANCE: 30gf~100gf
4. PEELING ANGLE: 165°~180°
5. PEELING SPEED: 300mm/minutes.



制图 DRAWN	变更内容 DESCRIPTION	日期 DATE	GENERAL TOLERANCE		制图 DRAWING	EMMA			料号 PART NO.	BX-SIM-1.5HJ		版本 REV.	A
			X.±0.50	X.°±5°	审核 CHECK	EVA	品名 TITLE	MICRO SIM CARD HINGED 8PIN H1.5 封装 封装	页次 SHEET	1/1			
			.X±0.25	.X°±3°	批准 APPROVAL	JADE	客户料号 CUTM.NO.						
			.XX±0.12		单位 UNITS	MM	比例 SCALE	1:1					